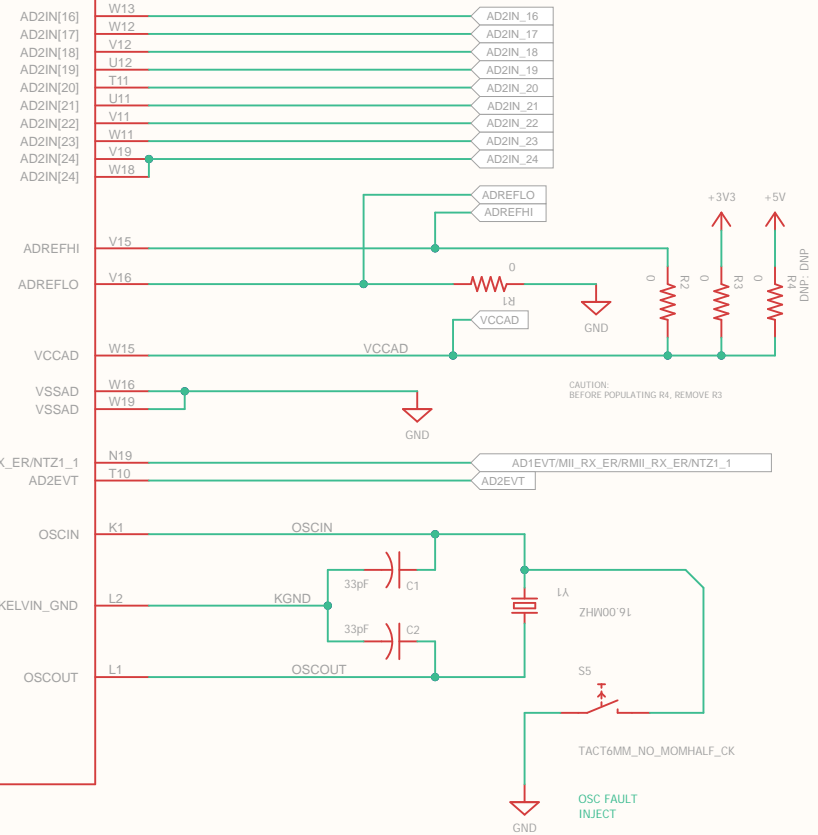
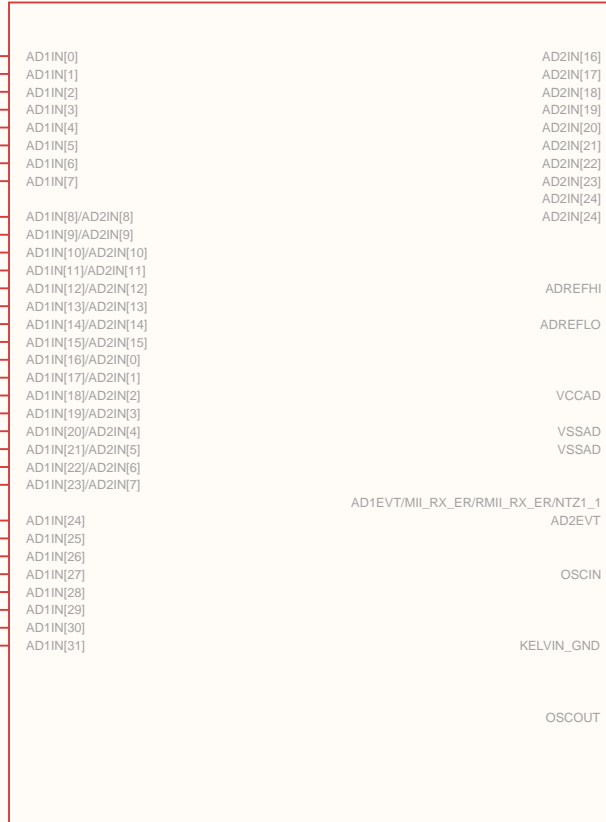
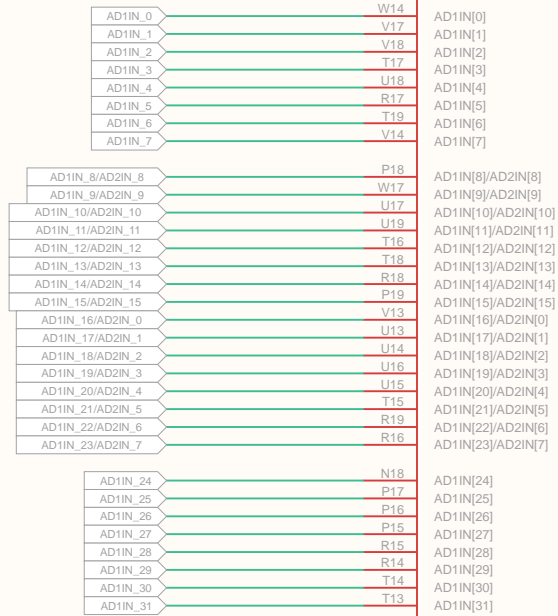
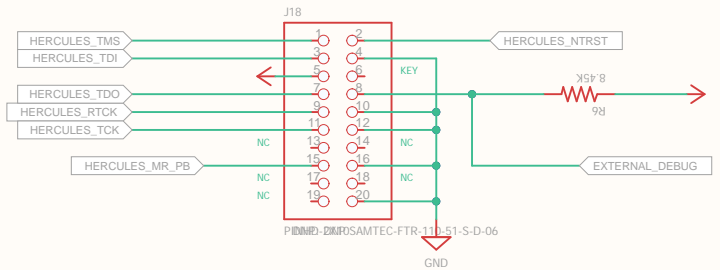
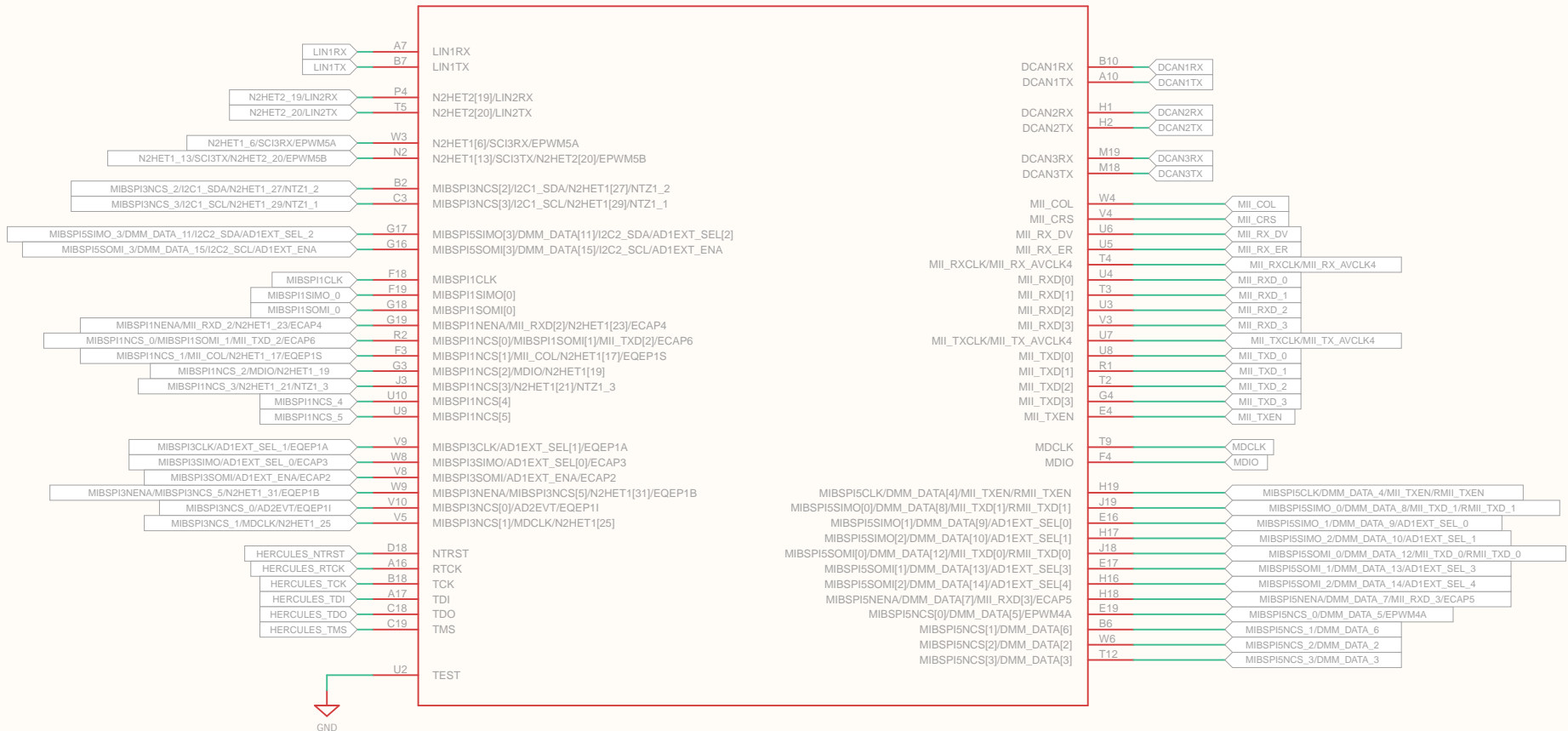


U1A
RM57L843_TMS570LC4357_ZWT_337

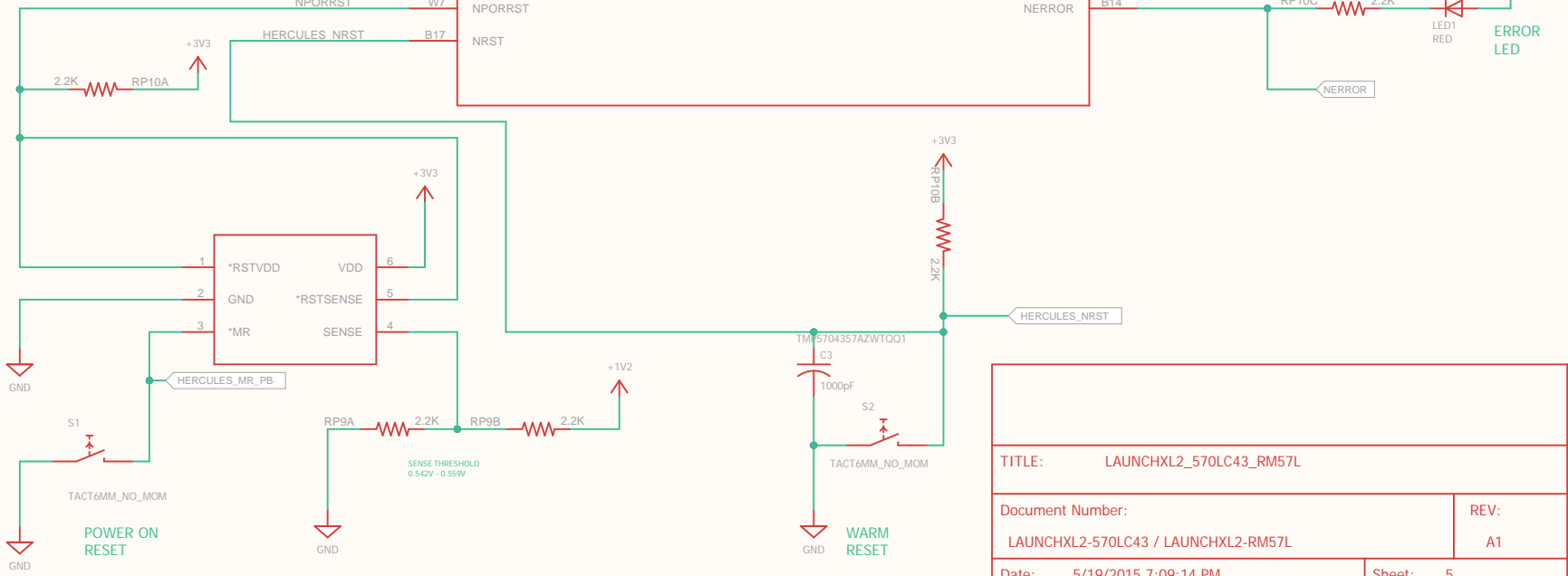
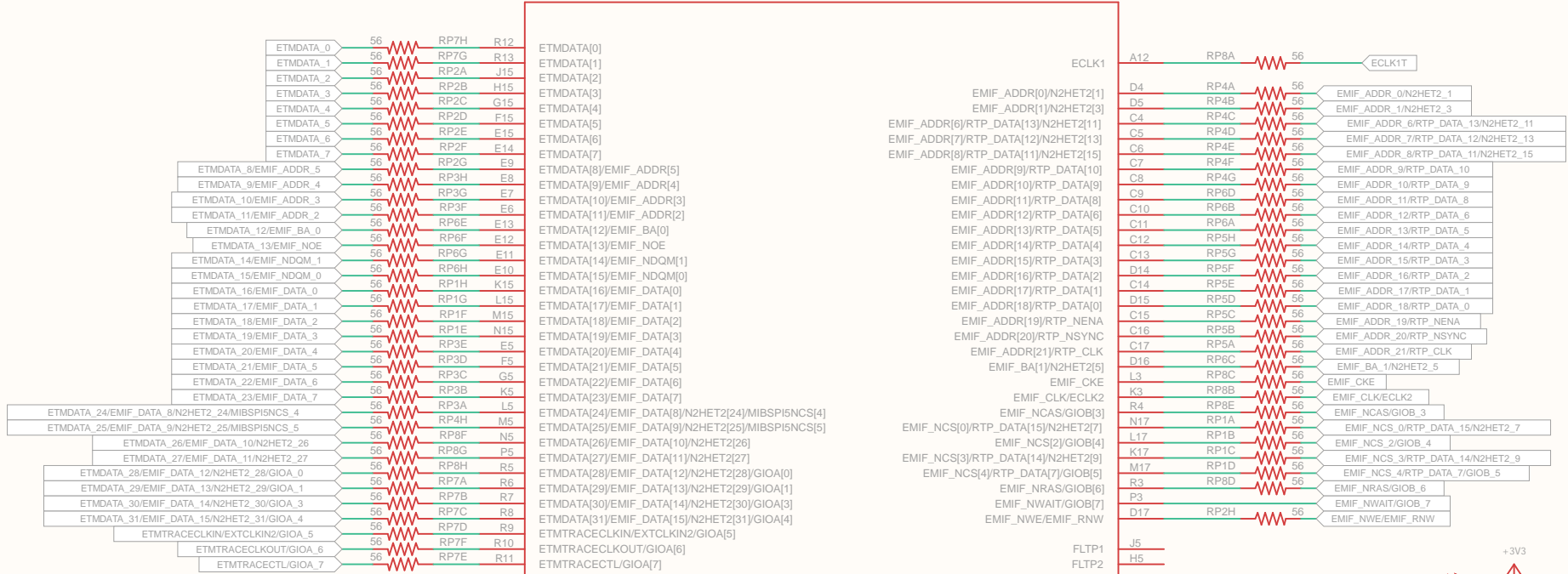


TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 2

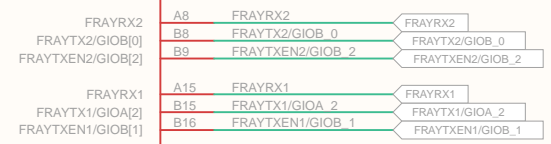
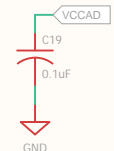
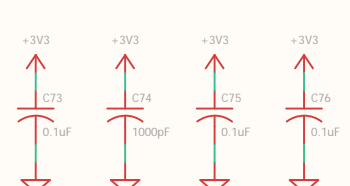
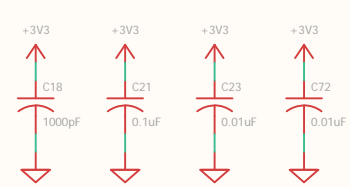
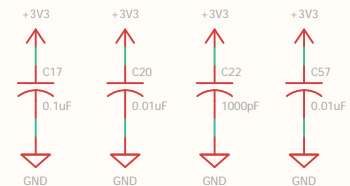
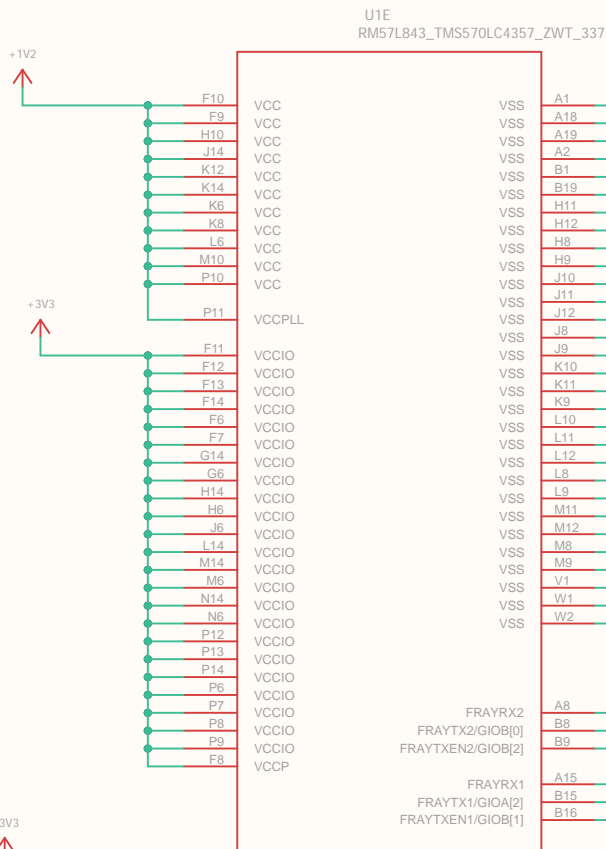
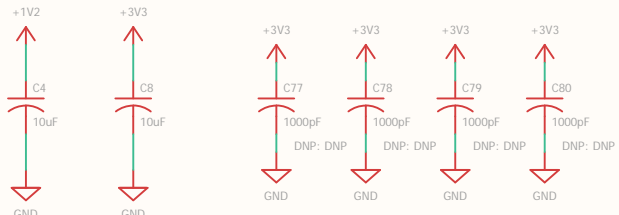
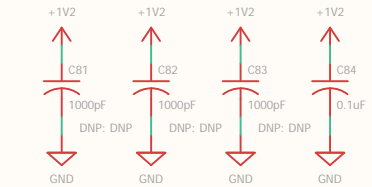
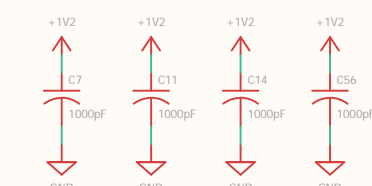
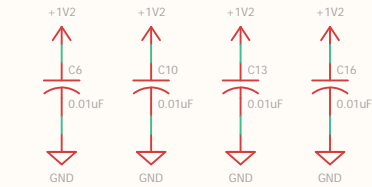
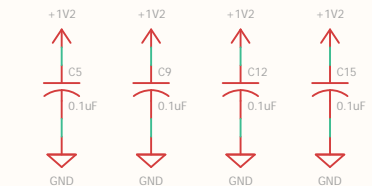
U1B
RM57L843_TMS570LC4357_ZWT_337



TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 3

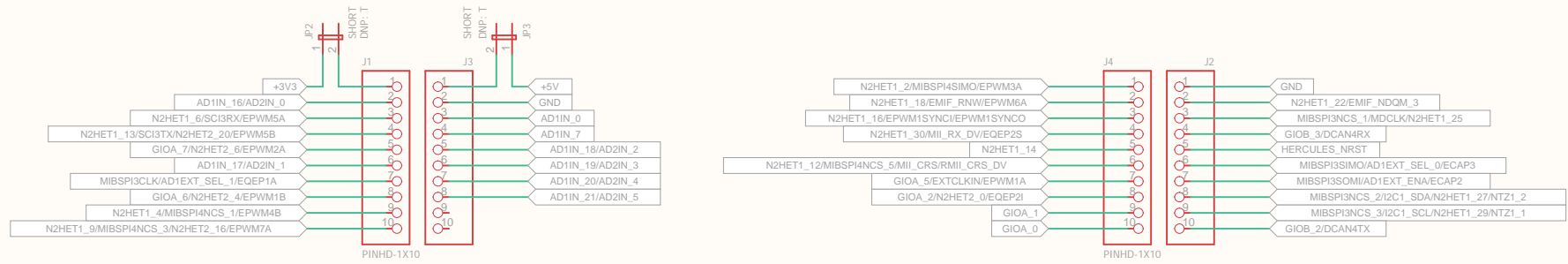


TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 5



TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 6

BOOSTER PACK SITE 1



Headers/Receptacles may be ordered from <http://launchpad.mlelectronics.com/>

NOTES:

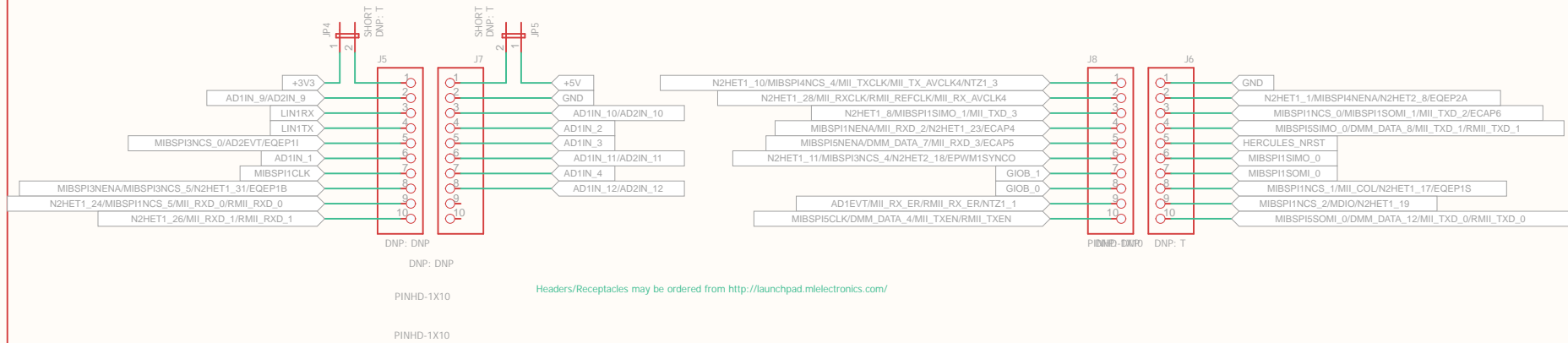
JP2 & JP3 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP2,JP3 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 7

BOOSTER PACK SITE 2



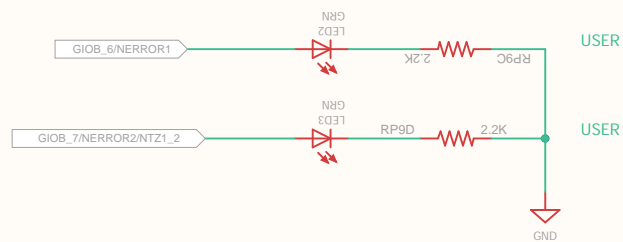
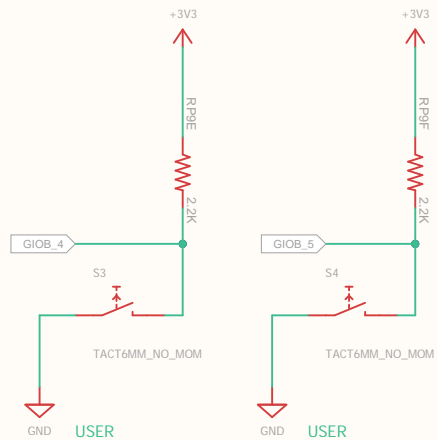
NOTES:

JP4 & JP5 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

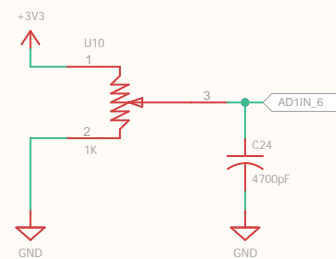
Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP4,JP5 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 8

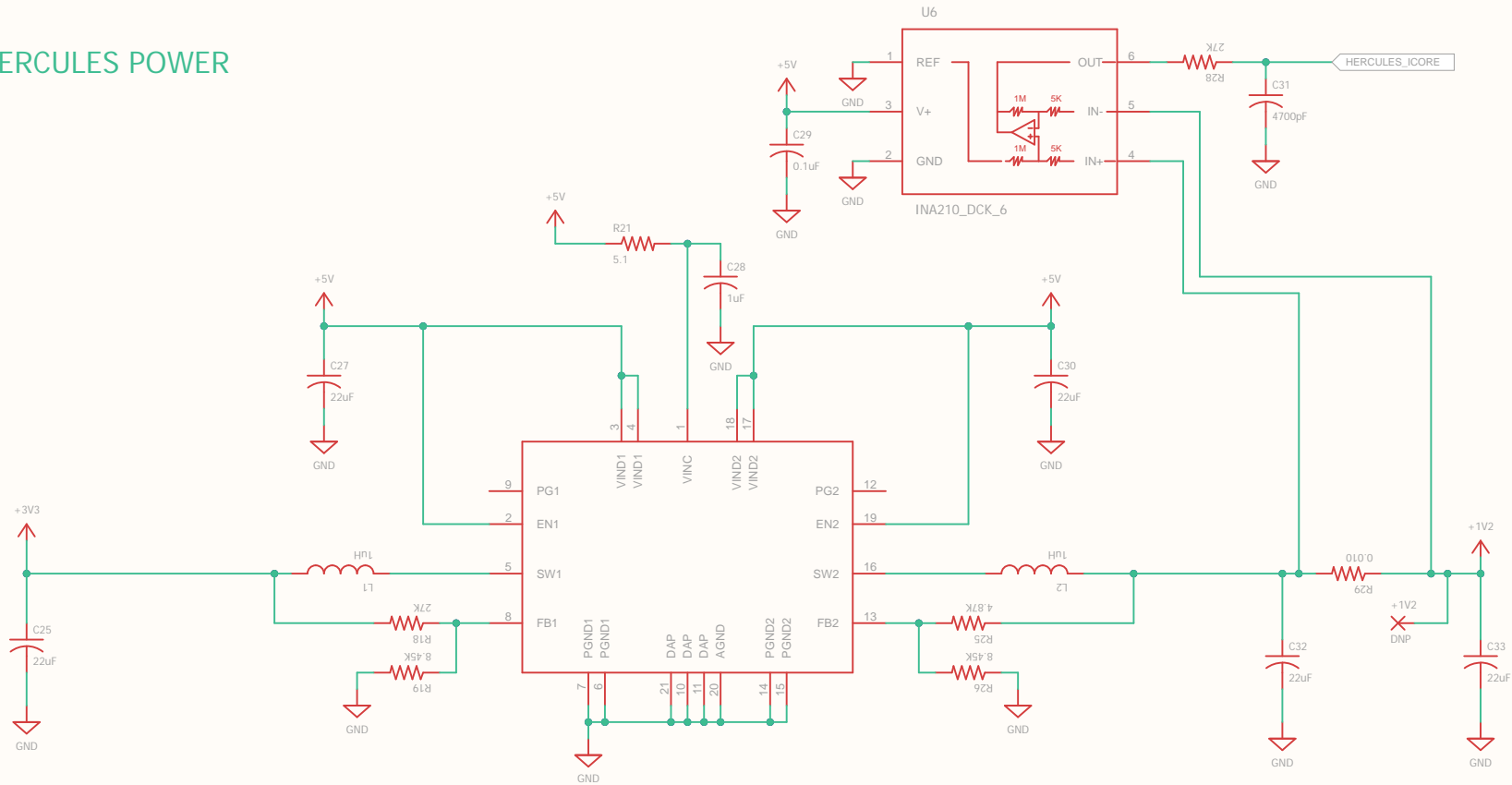


TRIM POT. FOR ANALOG INPUT
(REPLACES TEMP SENSOR)

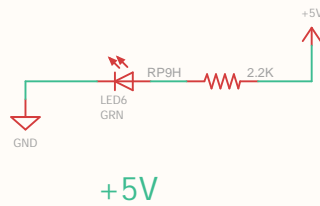


TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 10

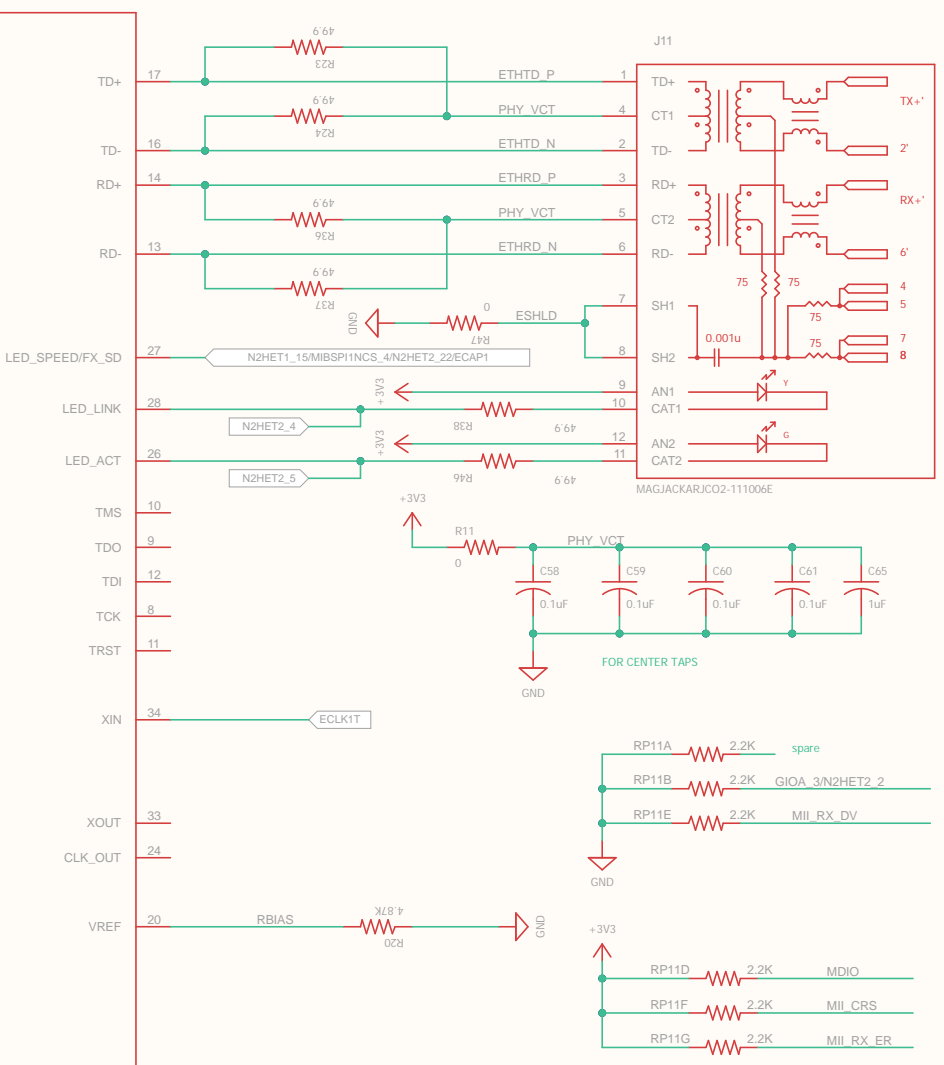
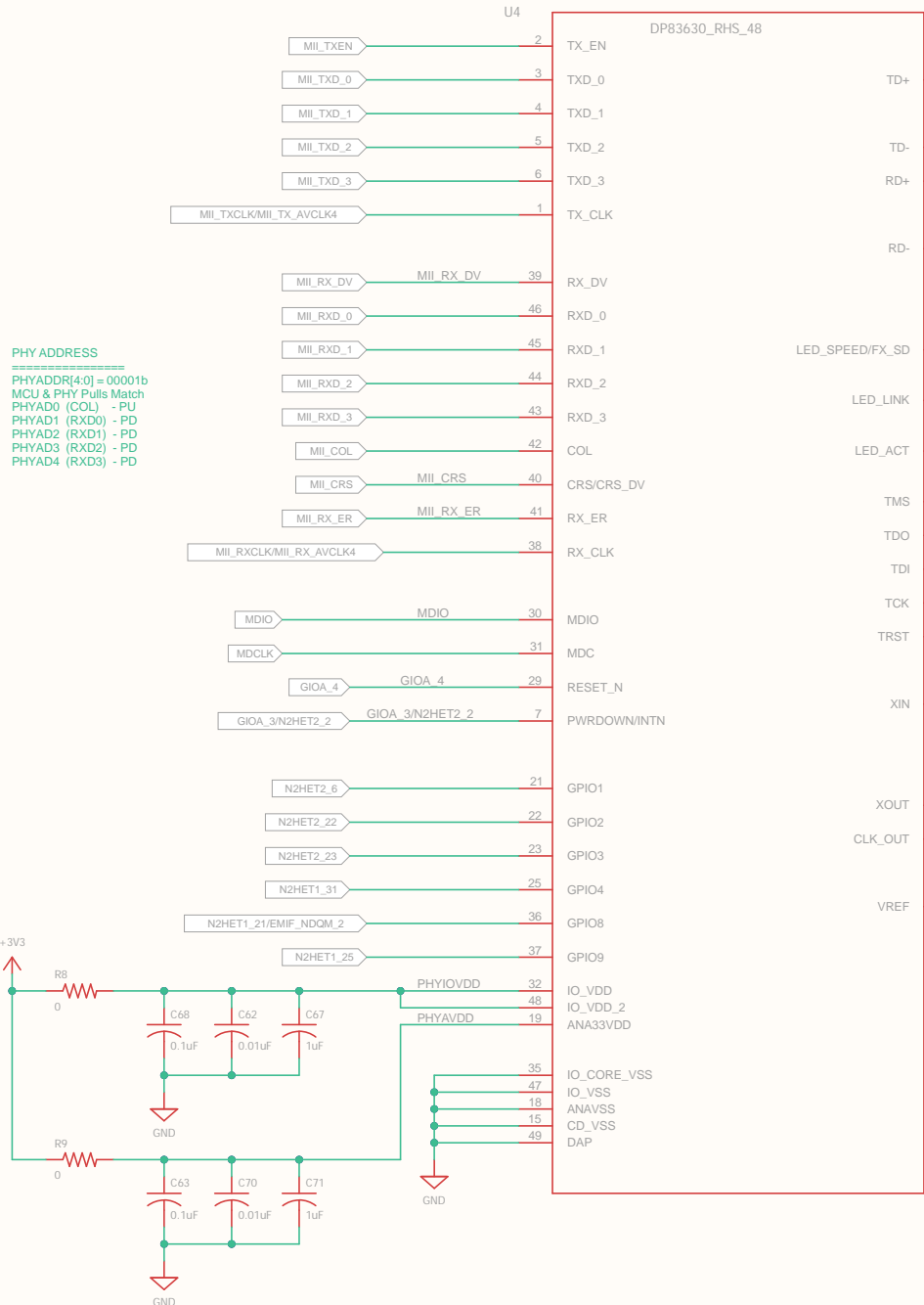
HERCULES POWER



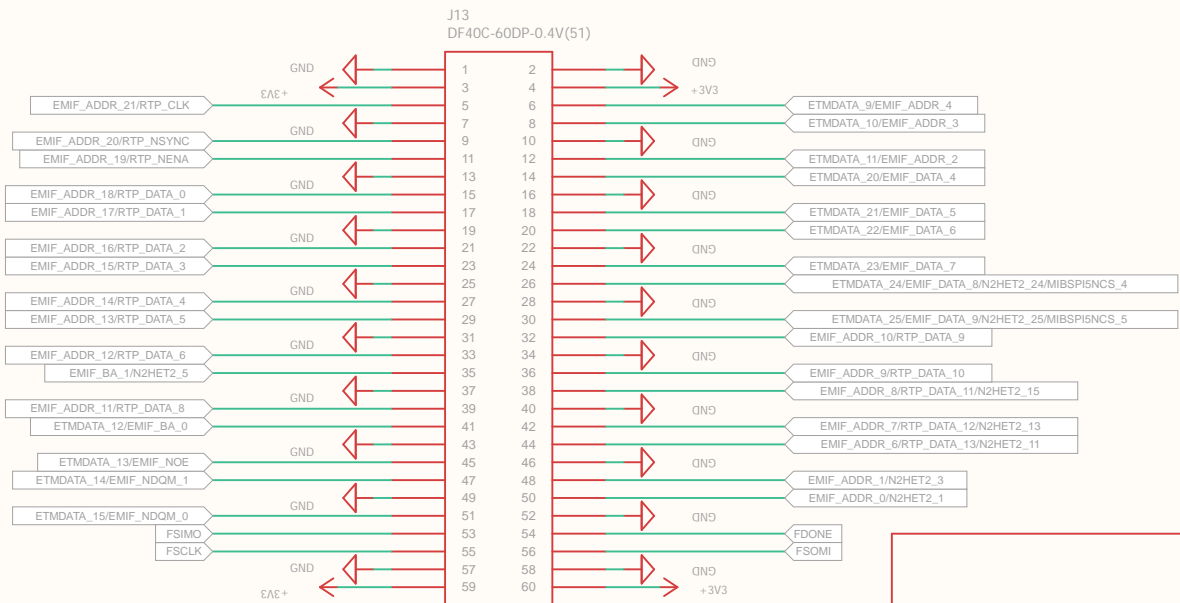
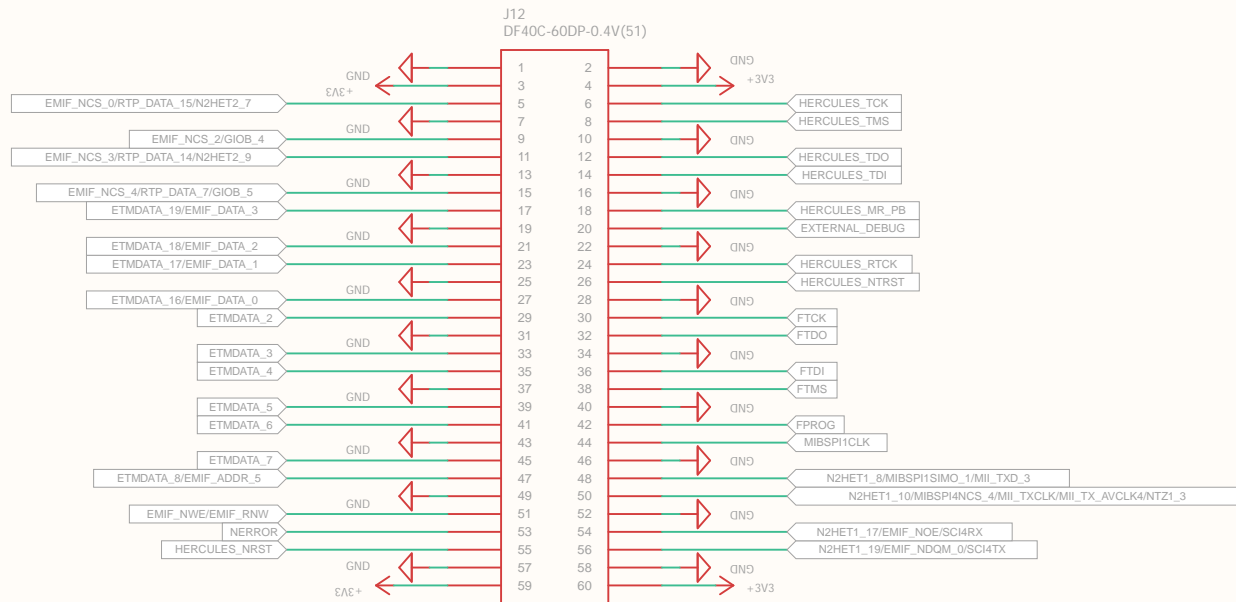
POWER INDICATOR LED



TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 11



TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 12

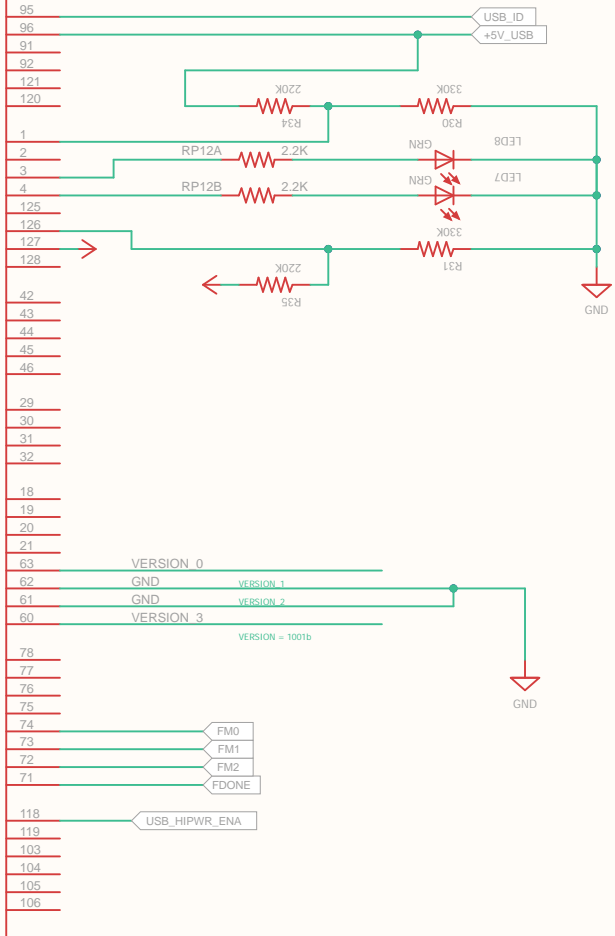


TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 13

XDS110 DEBUG PROBE

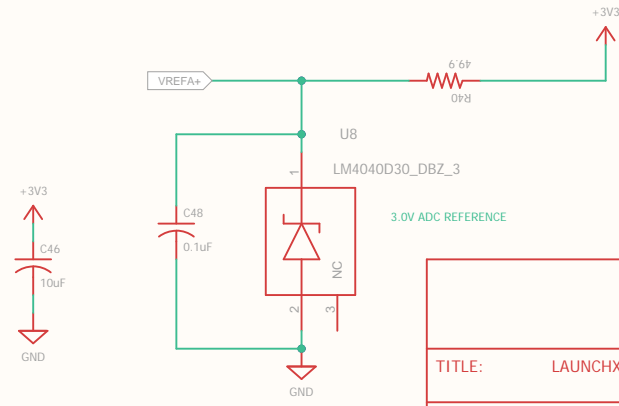
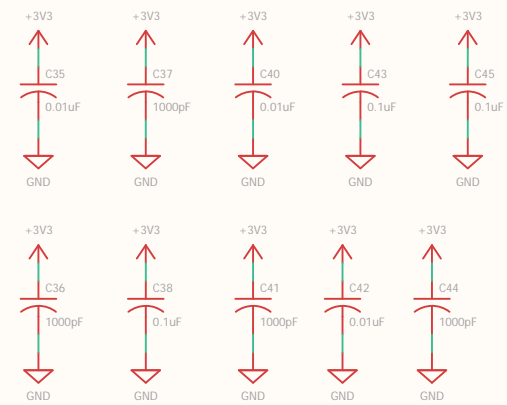
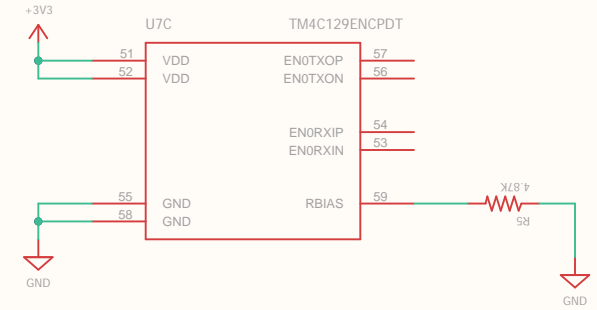
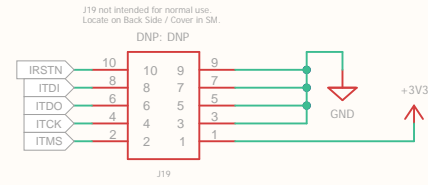
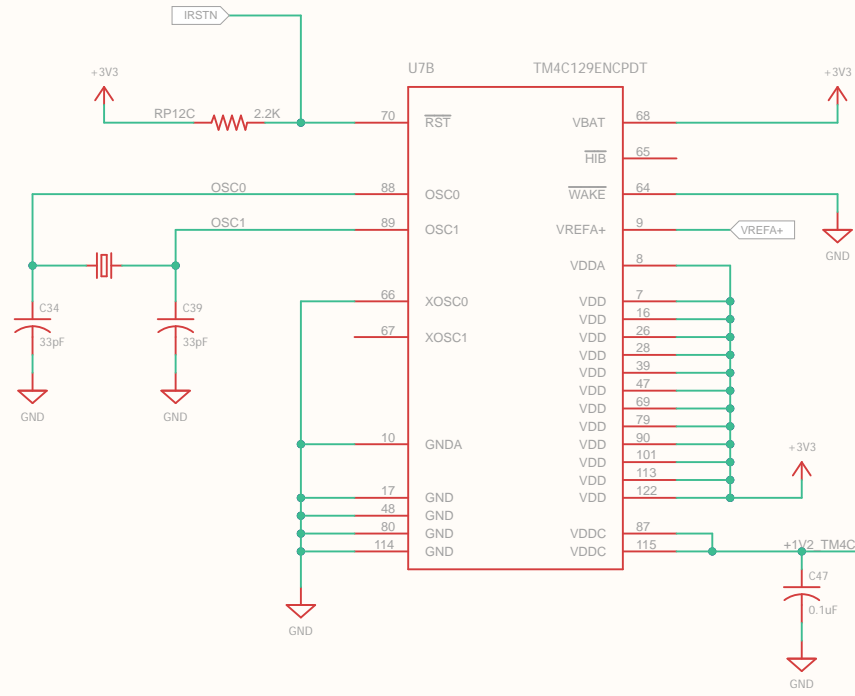
U7A

TM4C129ENCPT1



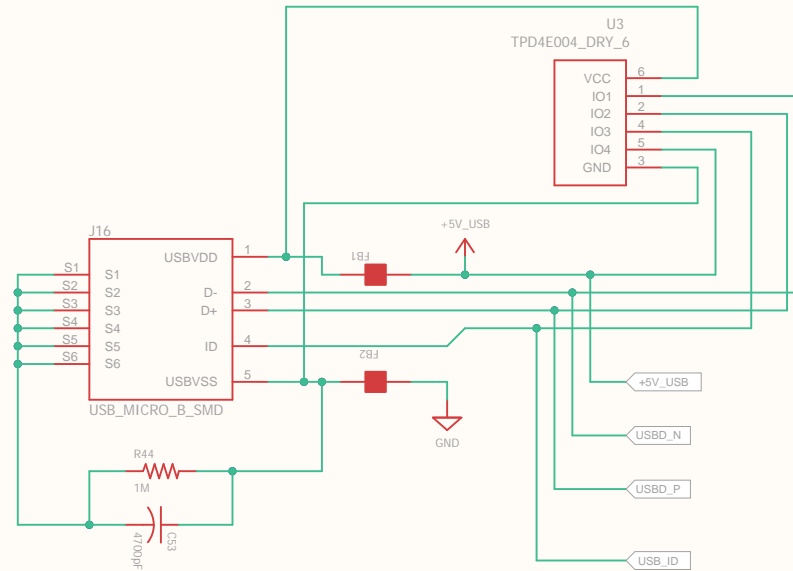
TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 15

XDS110 DEBUG PROBE



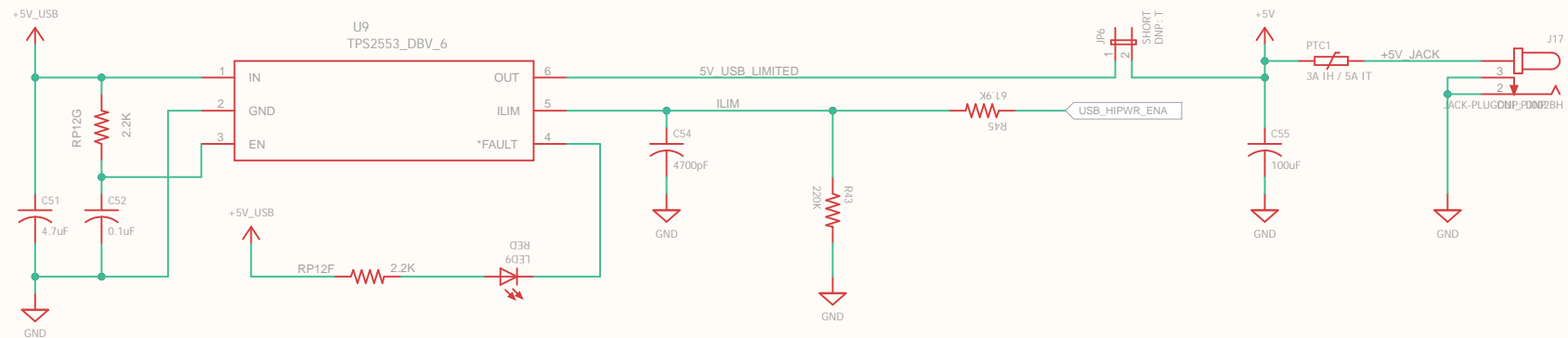
TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 16

C



CURRENT LIMITING FOR BUS POWERED OPERATION

REMOVE JUMPER TO POWER THROUGH BARREL JACK



GND POINTS



FIDUCIALS



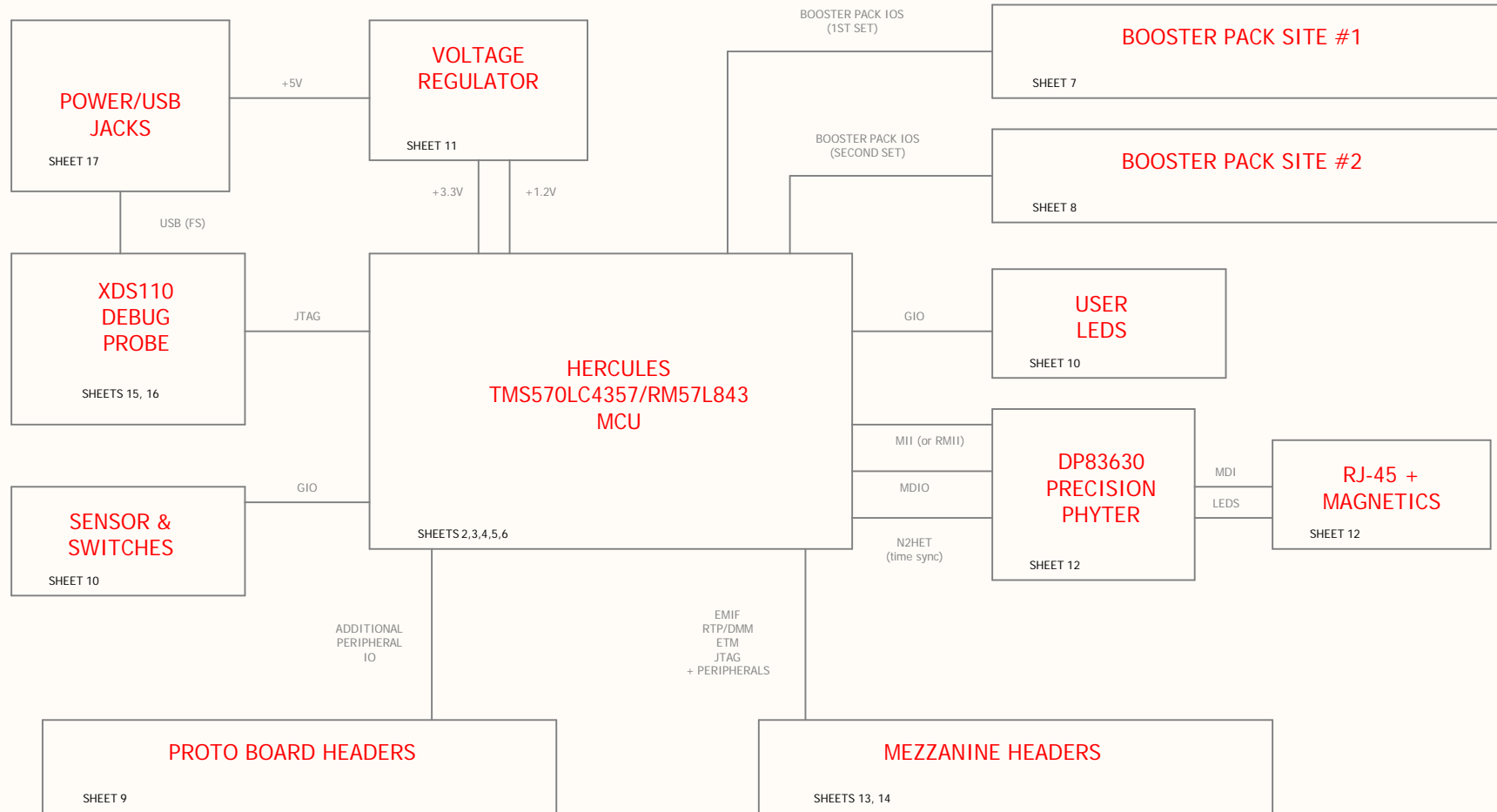
MNT HOLES



TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 17

LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

337 ZWT LAUNCHPAD XL2



1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 2

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 11

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 12

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

1

2

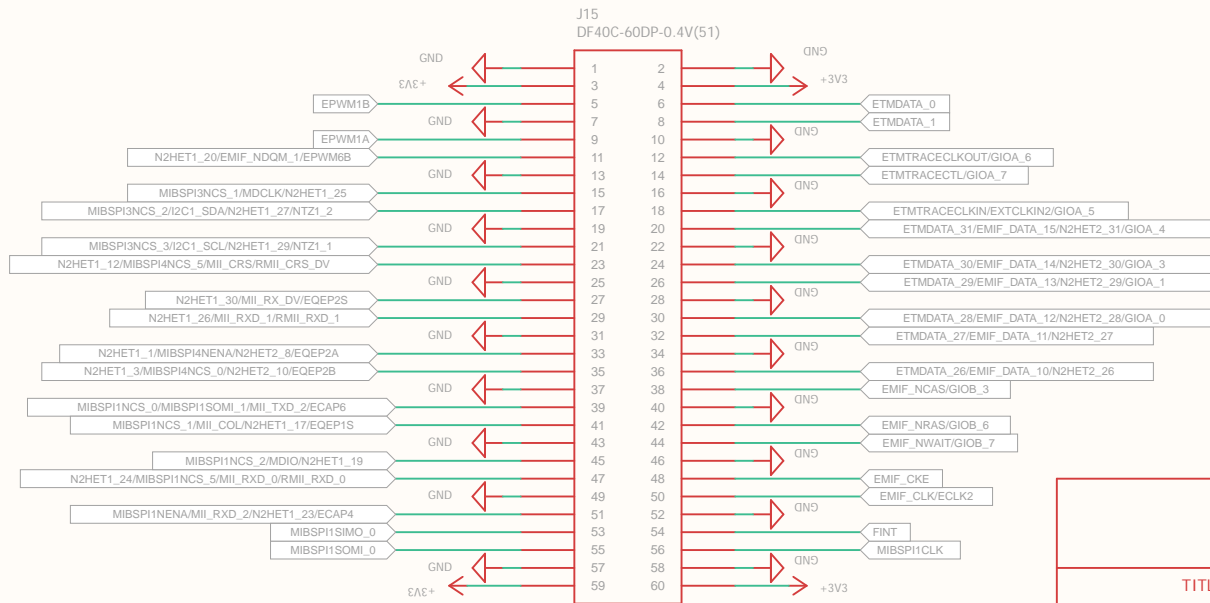
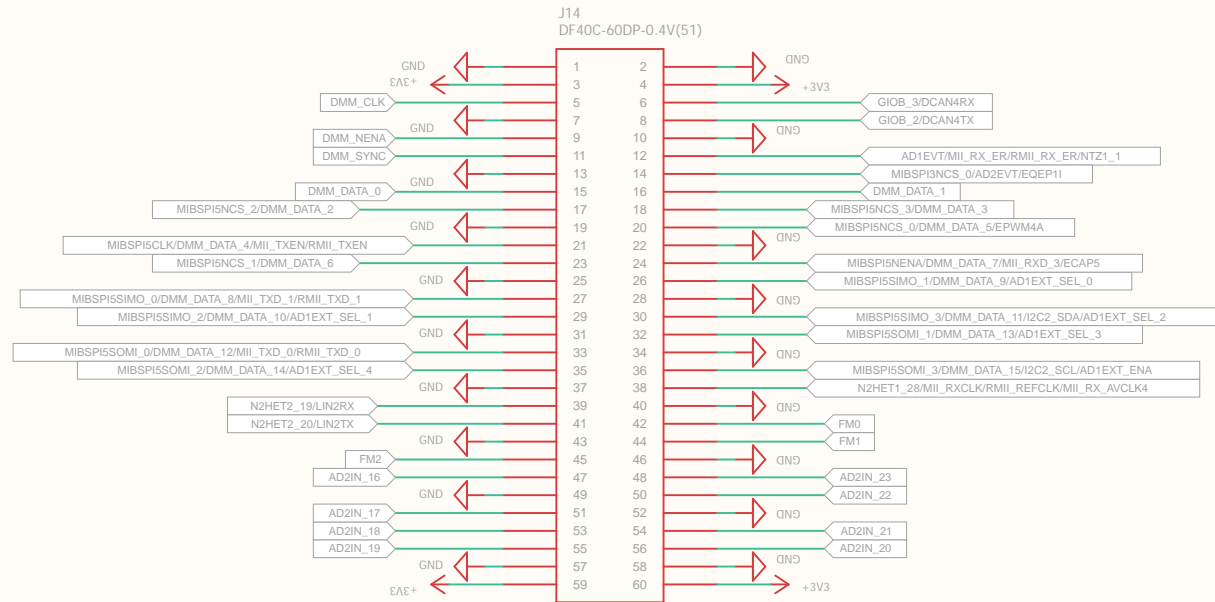
3

4

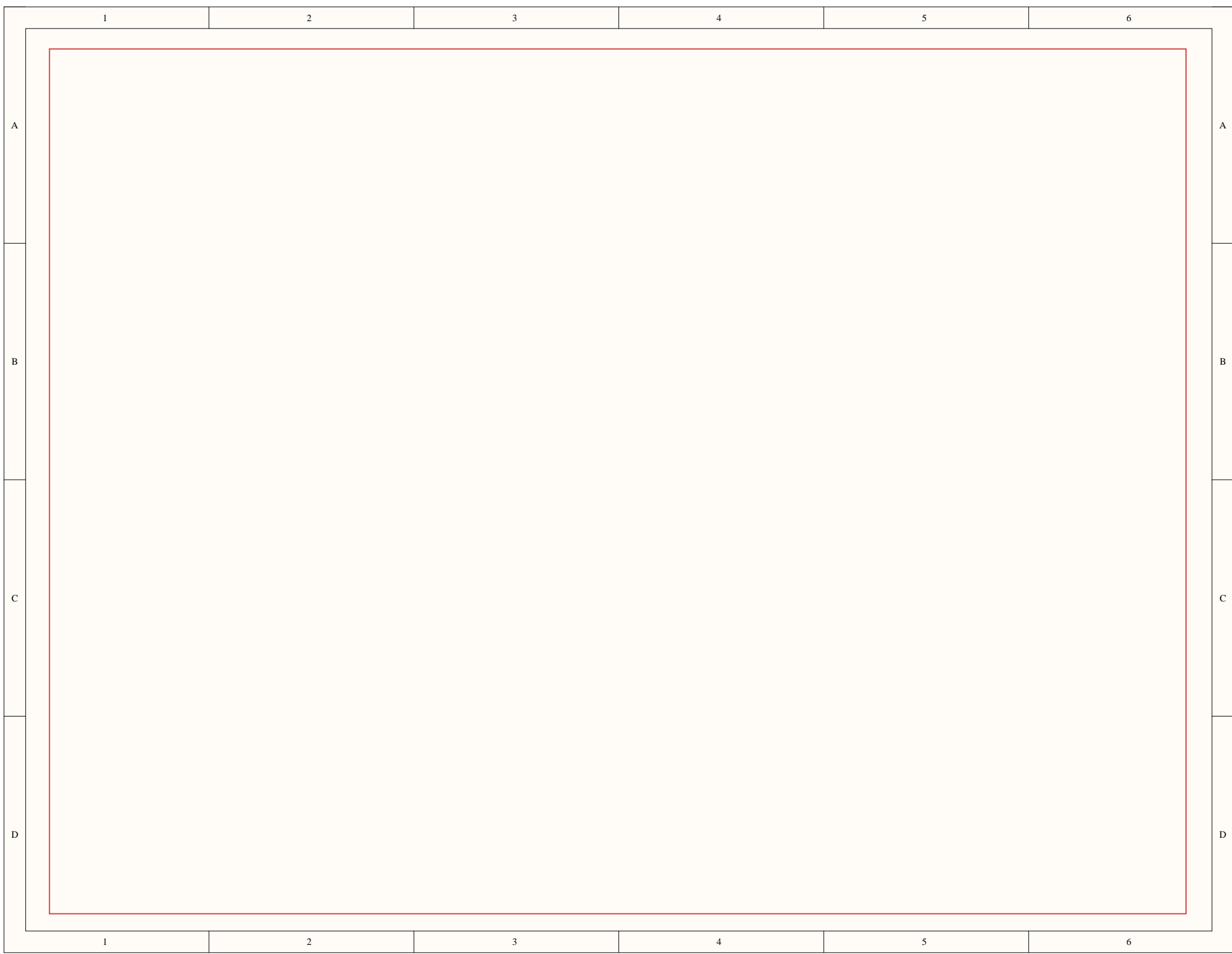
5

6

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 13



TITLE:	
Document Number:	REV:
>DOC_NUMBER	
Date:	Sheet: 14



1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 15

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 16

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 17

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 3

1

2

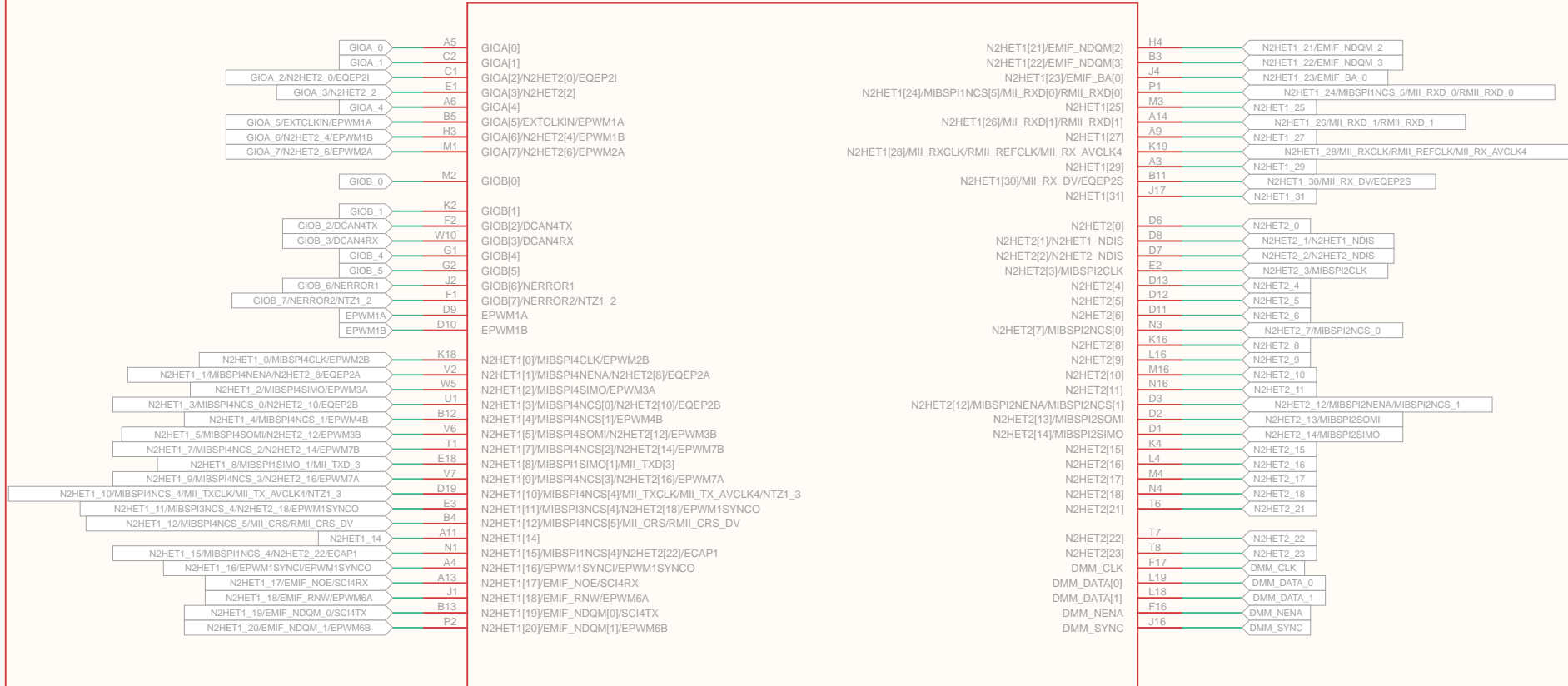
3

4

5

6

U1C
RM57L843_TMS570LC4357_ZWT_337



R12	ETMDATA[0]		
R13	ETMDATA[1]	ECLK1	A12
J15	ETMDATA[2]		
H15	ETMDATA[3]		D4
G15	ETMDATA[4]	EMIF_ADDR[0]/N2HET2[1]	D5
F15	ETMDATA[5]	EMIF_ADDR[1]/N2HET2[3]	C4
E15	ETMDATA[6]	EMIF_ADDR[6]/RTP_DATA[13]/N2HET2[11]	C5
E14	ETMDATA[7]	EMIF_ADDR[7]/RTP_DATA[12]/N2HET2[13]	C6
E9	ETMDATA[8]/EMIF_ADDR[5]	EMIF_ADDR[8]/RTP_DATA[11]/N2HET2[15]	C7
E8	ETMDATA[9]/EMIF_ADDR[4]	EMIF_ADDR[9]/RTP_DATA[10]	C8
E7	ETMDATA[10]/EMIF_ADDR[3]	EMIF_ADDR[10]/RTP_DATA[9]	C9
E6	ETMDATA[11]/EMIF_ADDR[2]	EMIF_ADDR[11]/RTP_DATA[8]	C10
E13	ETMDATA[12]/EMIF_BA[0]	EMIF_ADDR[12]/RTP_DATA[6]	C11
E12	ETMDATA[13]/EMIF_NOE	EMIF_ADDR[13]/RTP_DATA[5]	C12
E11	ETMDATA[14]/EMIF_NDQM[1]	EMIF_ADDR[14]/RTP_DATA[4]	C13
E10	ETMDATA[15]/EMIF_NDQM[0]	EMIF_ADDR[15]/RTP_DATA[3]	D14
K15	ETMDATA[16]/EMIF_DATA[0]	EMIF_ADDR[16]/RTP_DATA[2]	C14
L15	ETMDATA[17]/EMIF_DATA[1]	EMIF_ADDR[17]/RTP_DATA[1]	D15
M15	ETMDATA[18]/EMIF_DATA[2]	EMIF_ADDR[18]/RTP_DATA[0]	C15
N15	ETMDATA[19]/EMIF_DATA[3]	EMIF_ADDR[19]/RTP_NENA	C16
E5	ETMDATA[20]/EMIF_DATA[4]	EMIF_ADDR[20]/RTP_NSYSN	C17
F5	ETMDATA[21]/EMIF_DATA[5]	EMIF_ADDR[21]/RTP_CLK	D16
G5	ETMDATA[22]/EMIF_DATA[6]	EMIF_BA[1]/N2HET2[5]	L3
K5	ETMDATA[23]/EMIF_DATA[7]	EMIF_CKE	K3
L5	ETMDATA[24]/EMIF_DATA[8]/N2HET2[24]/MIBSPI5NCS[4]	EMIF_CLK/ECLK2	R4
M5	ETMDATA[25]/EMIF_DATA[9]/N2HET2[25]/MIBSPI5NCS[5]	EMIF_NCAS/GIOB[3]	N17
N5	ETMDATA[26]/EMIF_DATA[10]/N2HET2[26]	EMIF_NCS[0]/RTP_DATA[15]/N2HET2[7]	L17
P5	ETMDATA[27]/EMIF_DATA[11]/N2HET2[27]	EMIF_NCS[2]/GIOB[4]	K17
R5	ETMDATA[28]/EMIF_DATA[12]/N2HET2[28]/GIOA[0]	EMIF_NCS[3]/RTP_DATA[14]/N2HET2[9]	M17
R6	ETMDATA[29]/EMIF_DATA[13]/N2HET2[29]/GIOA[1]	EMIF_NCS[4]/RTP_DATA[7]/GIOB[5]	R3
R7	ETMDATA[30]/EMIF_DATA[14]/N2HET2[30]/GIOA[3]	EMIF_NRAS/GIOB[6]	P3
R8	ETMDATA[31]/EMIF_DATA[15]/N2HET2[31]/GIOA[4]	EMIF_NWAIT/GIOB[7]	D17
R9	ETMTRACECLKIN/EXTCLKIN2/GIOA[5]	EMIF_NWE/EMIF_RNW	
R10	ETMTRACECLKOUT/GIOA[6]		J5
R11	ETMTRACECTL/GIOA[7]		H5
W7	NPORRST	NERROR	B14
B17	NRST		

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 5

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 6

1

2

3

4

5

6

1

2

3

4

5

6

A

A

B

B

C

C

D

D

1

2

3

4

5

6

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 7

1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 8

1

2

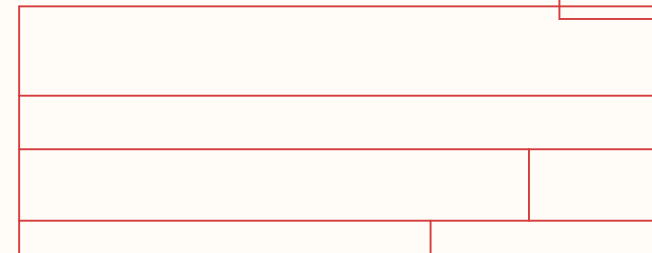
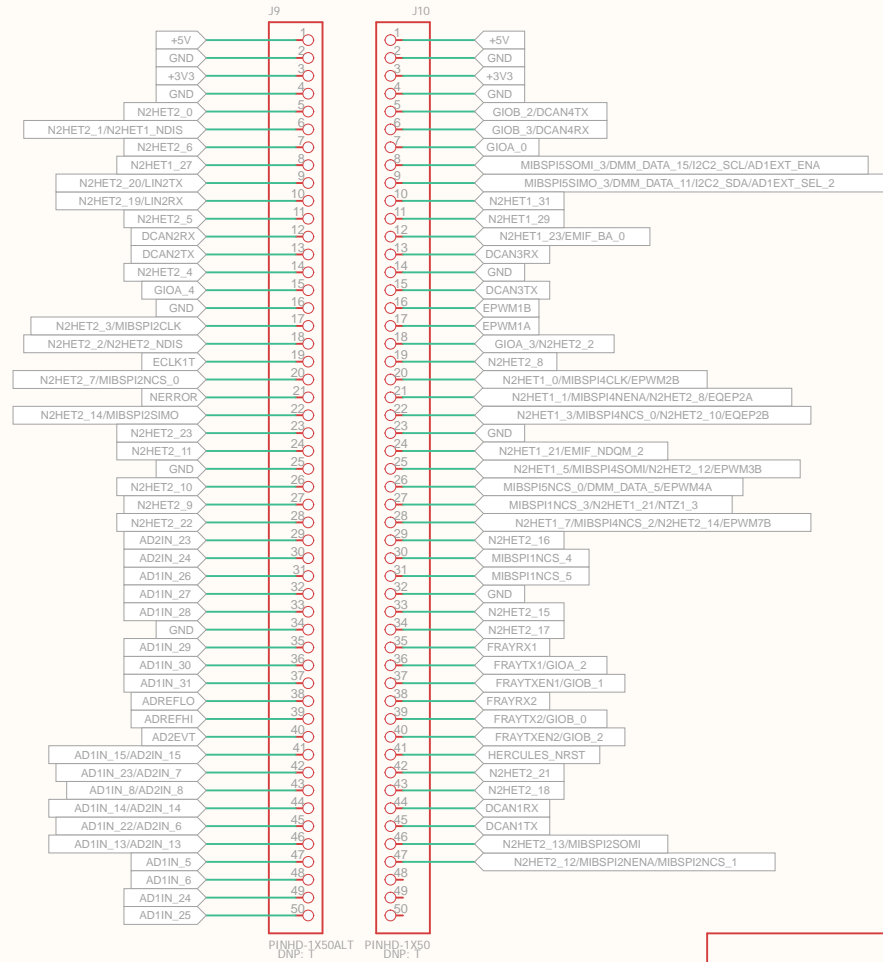
3

4

5

6

PROTO BOARD HEADERS



1

2

3

4

5

6

A

A

B

B

C

C

D

D

TITLE: LAUNCHXL2_570LC43_RM57L	
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L	REV: A1
Date: 5/19/2015 7:09:14 PM	Sheet: 10

1

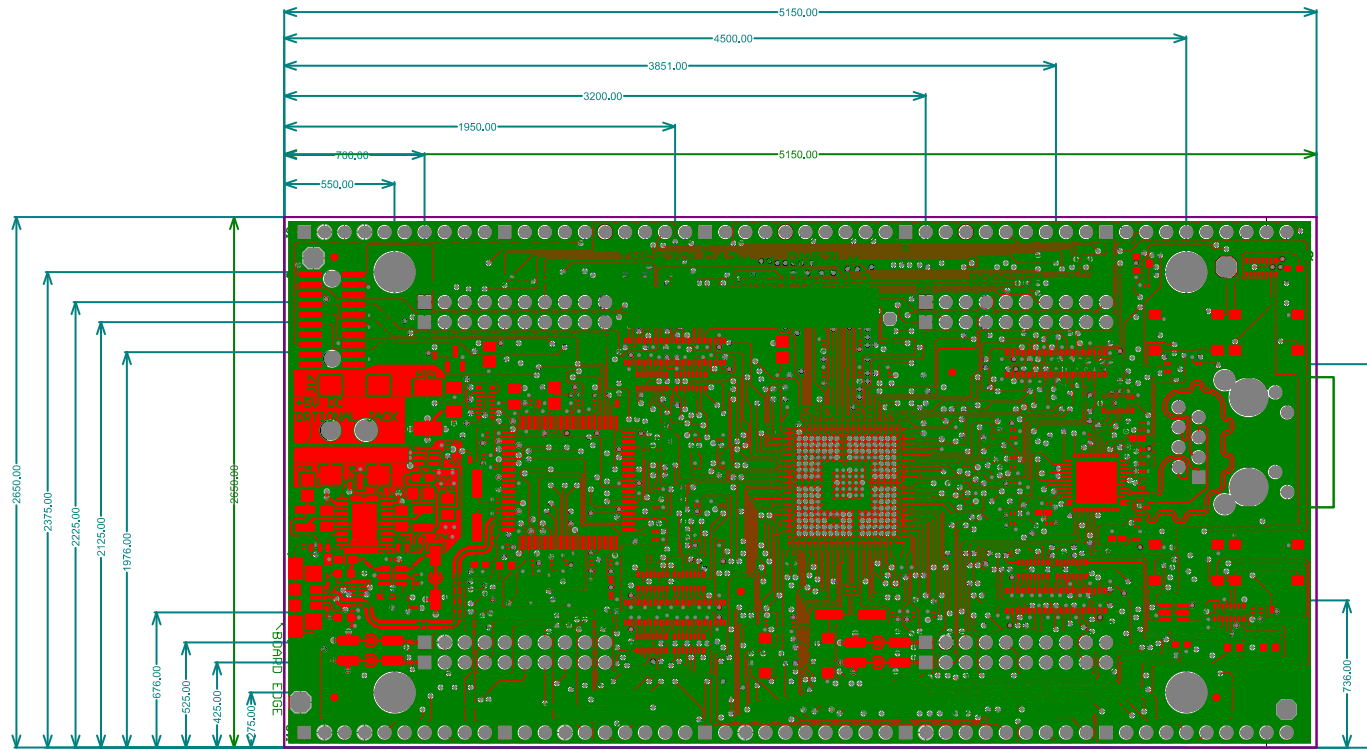
2

3

4

5

6



0.094 Diameter Hole x4

NOTES:

=====

- 1) All dimensions in mils
- 2) Build to IPC 6012 Class 2
- 3) FR4 Dielectric
- 4) Finish Thickness 0.062
- 5) Min 0.5 Oz Copper Top/Bottom Layers (10z is OK)
- 6) 0.5 Oz Copper Inner Layers
- 7) Lead-Free Soldermask Finish
- 8) Red LPI Soldermask Both Sides
- 9) White Silkscreen Both Sides
- 10) ROHS / REACH Required
- 11) UL94V-0 Required
- 12) J12, J13, J14, J15 dimensioned to centroids.

Layer Stackup:

=====

- .SST Top Side Silkscreen - Positive
 - .SMT Top Side Soldermask - Positive
 - .TOP Top Copper (Layer 1) - Positive
 - .IN1 Inner Copper (Layer 2) - Positive
 - .IN2 Inner Copper (Layer 3) - Positive
 - .BOT Bottom Copper (Layer 4) - Positive
 - .SMB Bottom Soldermask - Positive
 - .SSB Bottom Silkscreen - Positive
- Dielectric Thickness between Top Copper and IN1 Layer should be approximately 9.7mil (+/- 0.5mil is fine)

LAYER-STACK
01-16

Sym	Size(mil)	Tol(mil)	Qty	Plated
+	8	+/-0.5	1283	YES
x	10	+/-0.5	49	YES
□	36	+/-0.5	1	YES
◇	40	+/-0.5	196	YES
×	52	+/-0.5	2	YES
⊗	63	+/-0.5	1	YES
+	67	+/-0.5	2	YES
+	71	+/-0.5	1	YES
x	94	+/-0.5	4	YES
x	125	+/-0.5	2	YES

